

PATENT  
Atty. Dkt. No. APPM/007669.P1/PPC/ECP/CKIM

**IN THE CLAIMS:**

Please cancel claims 1-2, 4-25, and 29-32 and amend claim 3 as follows:

1-2. (Canceled)

3. (Currently Amended) An The electrochemical plating system of claim 2, comprising:

a substrate loading station positioned in communication with a mainframe processing platform;

at least one substrate plating cell positioned on the mainframe;

at least one substrate bevel cleaning cell positioned on the mainframe;

at least one spin rinse dry cell positioned on the mainframe in a substrate transfer path between the at least one substrate plating cell and the substrate loading station, wherein the at least one spin dry cell comprises:

    a cell bowl having an upstanding cylindrical wall;

    an annular and inwardly curving pressure reducing surface positioned on a top portion of the upstanding cylindrical wall;

    a fluid receiving shield extending radially inward from an upper portion of the upstanding cylindrical wall;

    a rotatable substrate support member centrally positioned in the cell bowl; and

    a fluid dispensing nozzle configured to dispense a rinsing solution onto an upper surface of a substrate positioned on the support member ;and

a stacked substrate annealing station positioned in communication with at least one of the mainframe and the loading station, each chamber in the stacked substrate annealing station having a substrate heating plate and a substrate cooling plate adjacently positioned therein.

4-32. (Canceled)